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3 Pin Out and Signal Description

3.1 Module Description

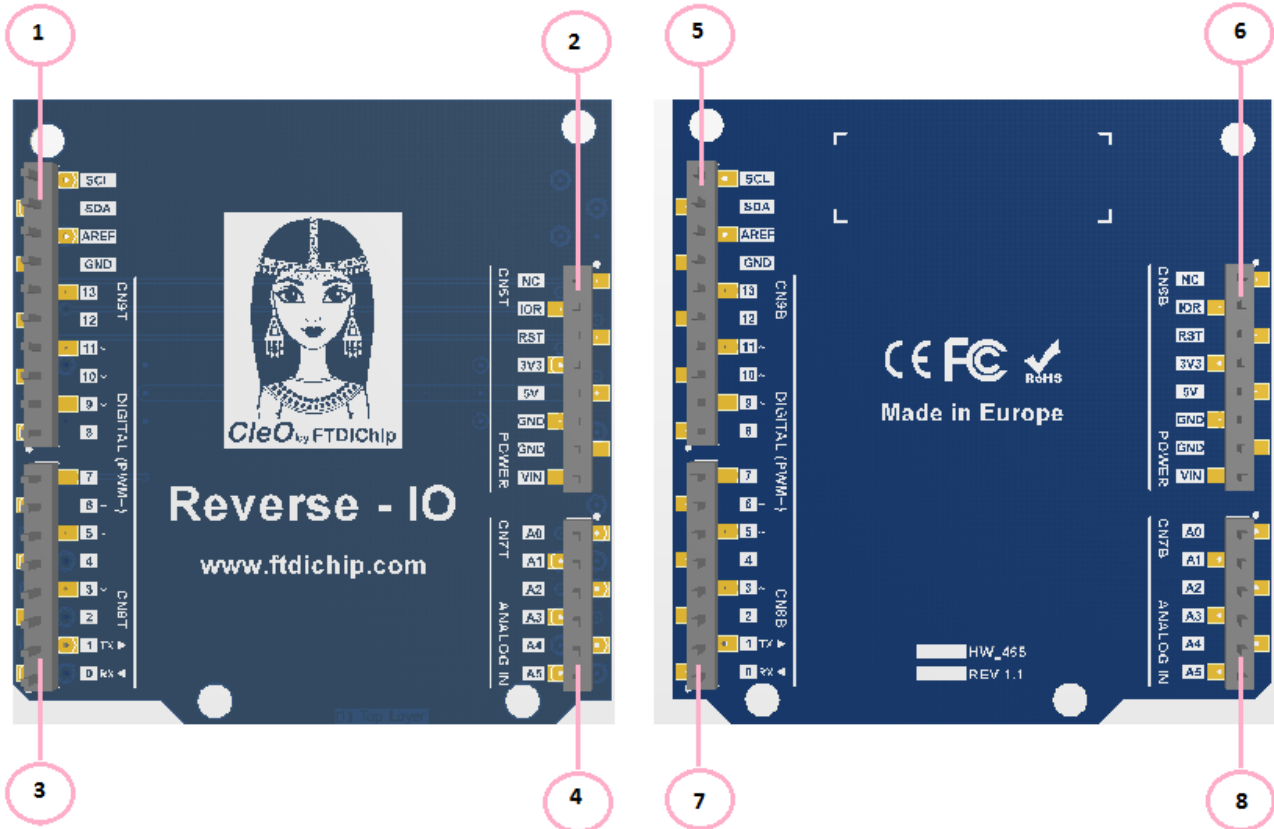


Figure 1 - CleO RIO Module Features

No	Feature	Reference Designator
1	1x10 position 2.54mm pitch SMT header	CN9T
2	1x8 position 2.54mm pitch SMT header	CN6T
3	1x8 position 2.54mm pitch SMT header	CN8T
4	1x6 position 2.54mm pitch SMT header	CN7T
5	1x10 position 2.54mm pitch SMT header	CN9B
6	1x8 position 2.54mm pitch SMT header	CN6B
7	1x8 position 2.54mm pitch SMT header	CN8B
8	1x6 position 2.54mm pitch SMT header	CN7B

Table 1 - CleO RIO Module Features Description

3.2 Module Signal Description

The pin description of **CN9T and CN9B** is the same and is given in Table 2.

Pin No	Pin Name	Description
1	-	NC
2	-	NC
3	D10	SPI Chip select option3
4	MOSI	SPI data from master side
5	MISO	SPI data to master side
6	SCK	SPI clock
7	GND	Ground
8	-	NC
9	-	NC
10	-	NC

Table 2 - CN9T and CN9B Pin Description

The pin description of **CN8T and CN8B** is the same and is given in Table 3.

Pin No	Pin Name	Description
1	-	NC
2	-	NC
3	D2	FT903 Interrupt request out option 1
4	D3	FT903 Interrupt request out option 2
5	-	NC
6	D5	SPI Chip select option1
7	-	NC
8	D7	SPI Chip select option2

Table 3 - CN8T and CN8B Pin Description

The pin description of **CN6T** and **CN6B** is the same and is given in Table 4.

Pin No	Pin Name	Description
1	-	NC
2	IOREF	IO reference voltage supply input
3	RESET	FT903 reset signal
4	-	NC
5	VDD_5V	5V Supply
6	GND	Ground
7	GND	Ground
8	-	NC

Table 4 - CN6T and CN6B Pin Description

4 Board Schematic

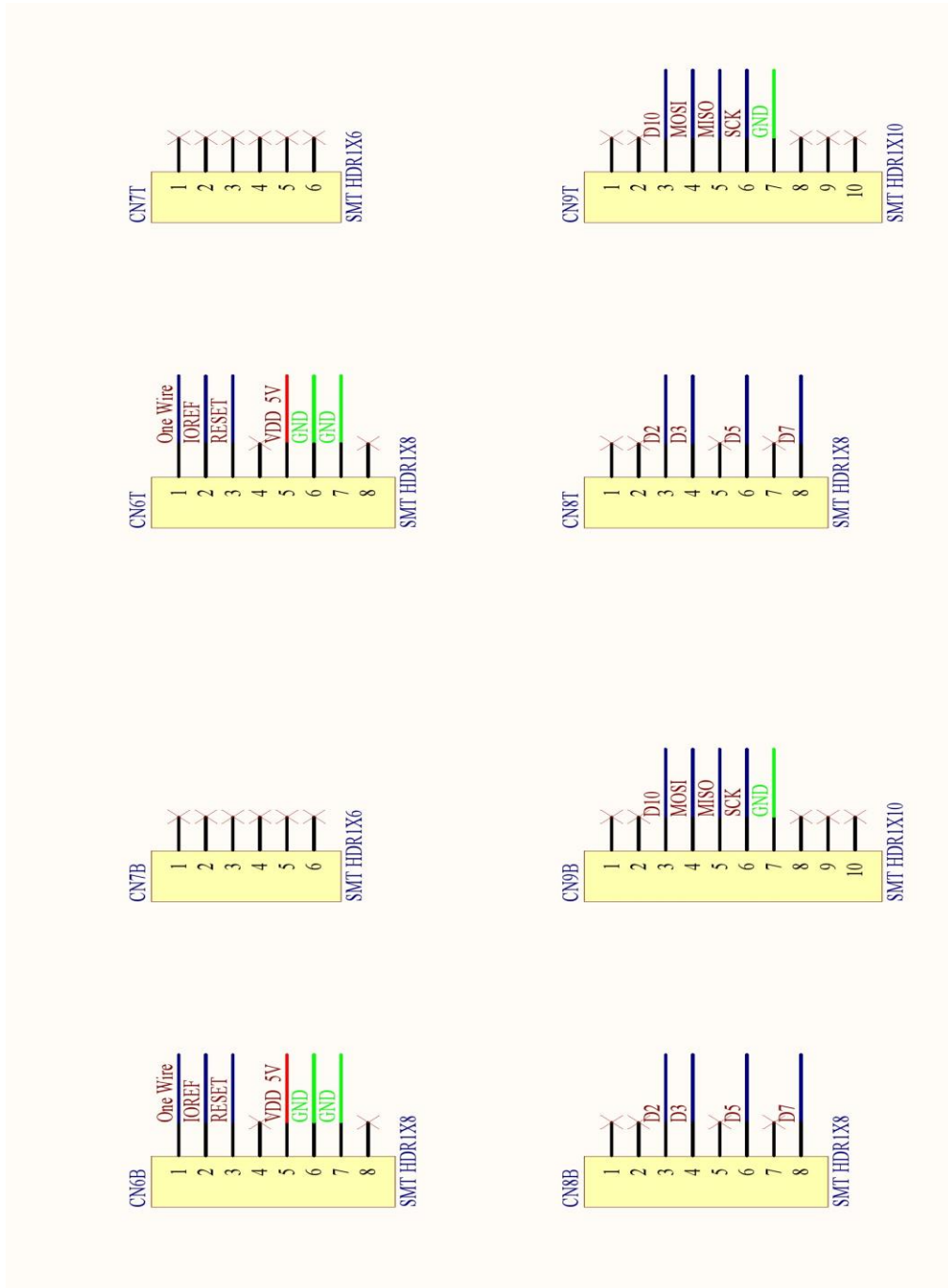


Figure 2 - Reverse I/O Schematic

5 Mechanical Dimensions

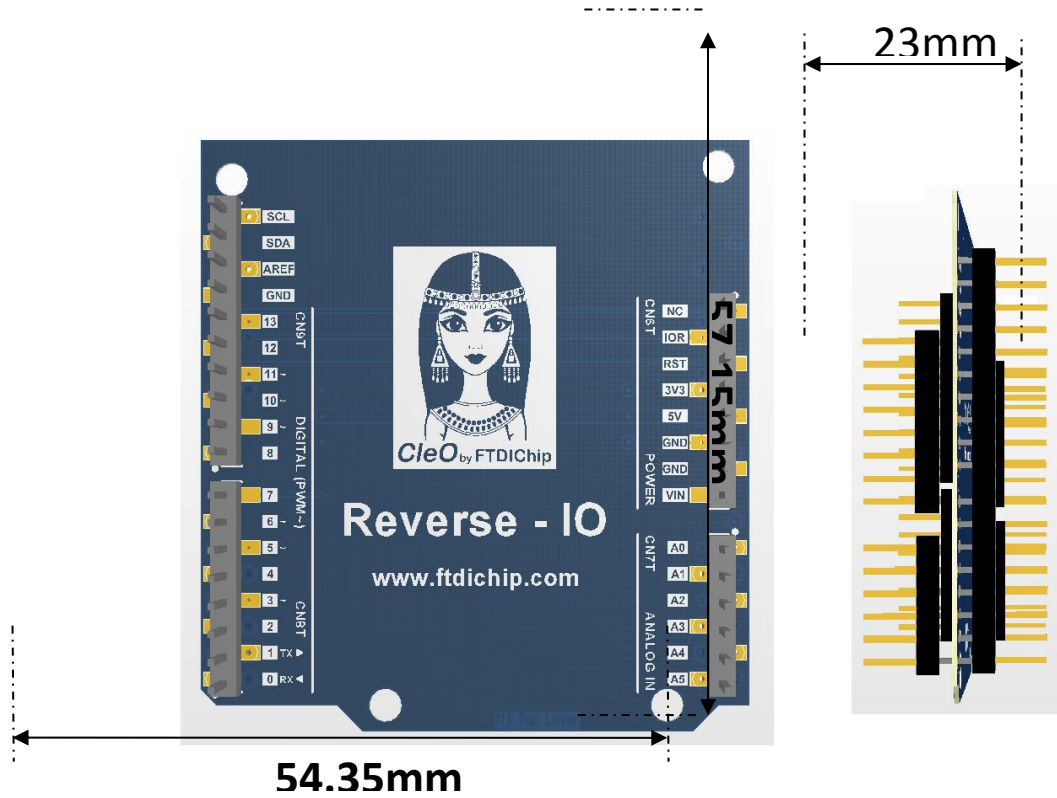


Figure 3 - CleO RIO Module Dimensions

6 Contact Information

Head Quarters – Singapore

Bridgetek Pte Ltd
178 Paya Lebar Road, #07-03
Singapore 409030
Tel: +65 6547 4827
Fax: +65 6841 6071

E-mail (Sales) sales.apac@brtchip.com
E-mail (Support) support.apac@brtchip.com

Branch Office – Taipei, Taiwan

Bridgetek Pte Ltd, Taiwan Branch
2 Floor, No. 516, Sec. 1, Nei Hu Road, Nei Hu District
Taipei 114
Taiwan, R.O.C.
Tel: +886 (2) 8797 5691
Fax: +886 (2) 8751 9737

E-mail (Sales) sales.apac@brtchip.com
E-mail (Support) support.apac@brtchip.com

Branch Office - Glasgow, United Kingdom

Bridgetek Pte. Ltd.
Unit 1, 2 Seaward Place, Centurion Business Park
Glasgow G41 1HH
United Kingdom
Tel: +44 (0) 141 429 2777
Fax: +44 (0) 141 429 2758

E-mail (Sales) sales.emea@brtchip.com
E-mail (Support) support.emea@brtchip.com

Branch Office – Vietnam

Bridgetek VietNam Company Limited
Lutaco Tower Building, 5th Floor, 173A Nguyen Van
Troj,
Ward 11, Phu Nhuan District,
Ho Chi Minh City, Vietnam
Tel : 08 38453222
Fax : 08 38455222

E-mail (Sales) sales.apac@brtchip.com
E-mail (Support) support.apac@brtchip.com

Web Site

<http://brtchip.com/>

Distributor and Sales Representatives

Please visit the Sales Network page of the [Bridgetek Web site](#) for the contact details of our distributor(s) and sales representative(s) in your country.

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Appendix A – References

Document References

NA

Acronyms and Abbreviations

Terms	Description
TFT	Thin Film Transistor
SPI	Serial Peripheral Interface
SMT	Surface Mount Technology

Appendix B - List of Figures and Tables

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Appendix C – Revision History

Document Title: CleO- RIO Module Datasheet
 Document Reference No.: BRT_000017
 Clearance No.: BRT#022
 Product Page: <http://brtchip.com/m-cleo/>
 Document Feedback: [Send Feedback](#)

Revision	Changes	Date
Version 1.0	Initial Release	2016-04-20
Version 1.1	Dual branding to reflect the migration of the product to the Bridgetek name – logo changed, copyright changed, contact information changed	2016-09-16